L Number	Hits	Search Text	DB	Time stamp
1	607	(356/614-624,3.01-3.09,3.1-3.12 250/559.38).ccls. and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/14 09:46
2	85	(356/614-624,3.01-3.09,3.1-3.12 250/559.38).ccls. and (semiconductor or wafer) and (line near4 beam)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/14 09:46
3	10	(356/614-624,3.01-3.09,3.1-3.12 250/559.38).ccls. and (semiconductor or wafer) and (line near4 beam) and (field near3 view)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/14 10:25
4	1	5969820.pn.	USPAT	2003/11/14 10:26
5	2	5969820.URPN.	USPAT	2003/11/14 10:33